

0.8A SCR's

Sensitive Gate / Silicon Controlled Rectifiers

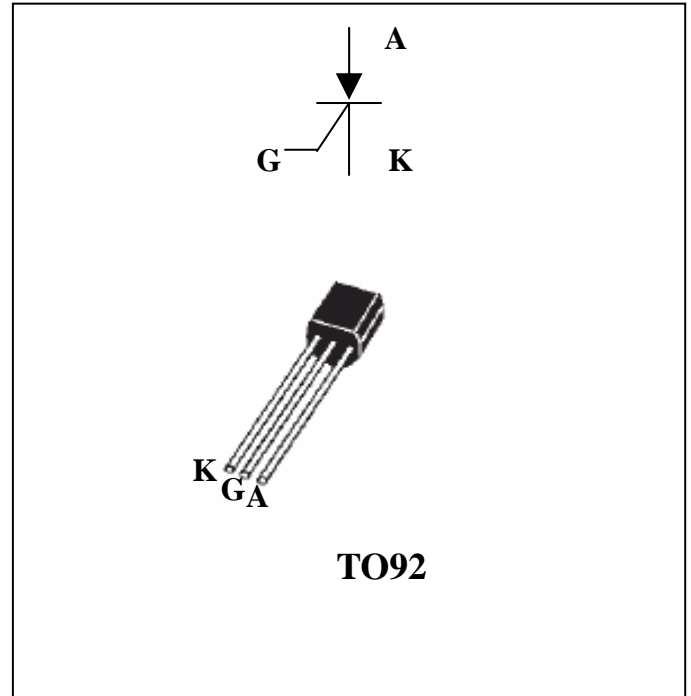
Main features

Symbol	Value	Unit
$I_{T(RMS)}$	0.8A	A
V_{DRM}/V_{RRM}	400 and 600	V
$I_{GT(Q1)}$	200	uA

DESCRIPTION

These devices are intended to be interfaced directly to microcontrollers, logic integrated circuits and other low power gate trigger circuits.

Weight : 0.22 gram



Absolute maximum ratings

Symbol	Parameter	Value	Unit	
$I_{T(RMS)}$	RMS on-state current (180° conduction angle)	0.8	A	
I_{TSM}	Non repetitive surge on-state current (1/2 Cycle, Sine Wave , T_j initial=25°C)	F = 50Hz t = 10ms	7	A
		F = 60Hz t = 8.3ms	8	
I^2t	I^2t Value for fusing	$t_p = 10ms$	0.24	A ² s
dl/dt	Critical rate of rise of on-state current $I_G = 10mA$ $di_G = 0.1A/us$		30	A/us
I_{GM}	Peak gate current		1	A
$P_{G(AV)}$	Average gate power dissipation		0.1	W
T_{stg} T_j	Storage junction temperature range Operating junction temperature range		-40 to +150 -40 to +110	°C

Electrical characteristics ($T_j = 25^\circ\text{C}$, unless otherwise specified)

Symbol	Test conditions		MCR100-			Unit
			6S	6	8	
$V_{\text{DRM}}, V_{\text{RRM}}$			400	400	600	V
$I_{\text{GT}}(1)$	$V_{\text{D}} = 7\text{V}$ $R_{\text{L}} = 100\ \Omega$	MAX.	25	200	200	μA
V_{GT}		MAX.	0.8			V
$I_{\text{H}}(2)$	$I_{\text{T}} = 50\ \text{mA}$ $R_{\text{GK}} = 1\text{k}\Omega$	MAX.	5			mA
I_{L}	$I_{\text{G}} = 1\text{mA}$ $R_{\text{GK}} = 1\text{k}\Omega$	MAX.	10			mA
$dV/dt(2)$	$V_{\text{D}} = 67\% V_{\text{DRM}}$ $R_{\text{GK}} = 1\text{k}\Omega$ $T_j = 110^\circ\text{C}$	MIN.	80	75	75	V/us

Static characteristics

Symbol	Test conditions			Value	Unit	
$V_{\text{T}}(2)$	$I_{\text{TM}} = 1\text{A}$	$t_{\text{p}} = 380\ \mu\text{s}$	$T_j = 25^\circ\text{C}$	MAX.	1.7	V
I_{DRM} I_{RRM}	$V_{\text{DRM}} = V_{\text{RRM}}$		$T_j = 25^\circ\text{C}$	MAX.	10	μA
			$T_j = 110^\circ\text{C}$		0.1	mA

Thermal resistance

Symbol	Parameter	Value	Unit
$R_{\text{th}}(j-l)$	Junction to lead for DC	80	$^\circ\text{C}/\text{W}$
$R_{\text{th}}(j-a)$	Junction to ambient	150	$^\circ\text{C}/\text{W}$



Fig.1 : Maximum average power dissipation versus average on-state current.

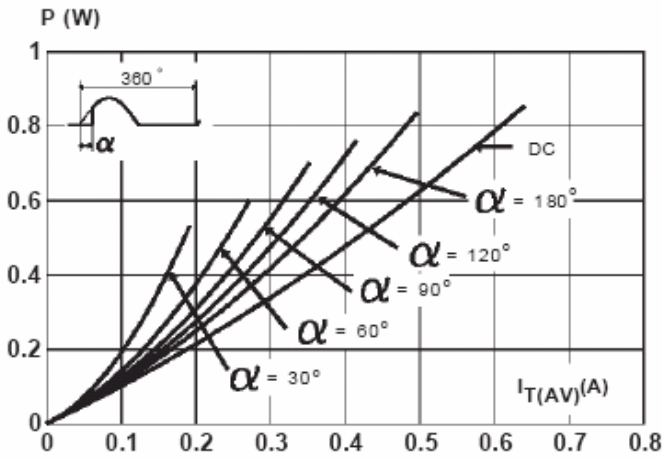


Fig.2 : Correlation between maximum average power dissipation and maximum allowable temperature (Tamb and Ttab).

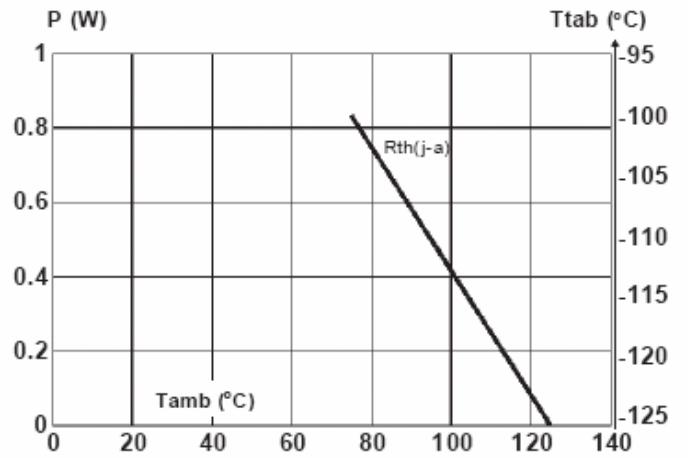


Fig.3 : Average on-state current versus tab temperature.

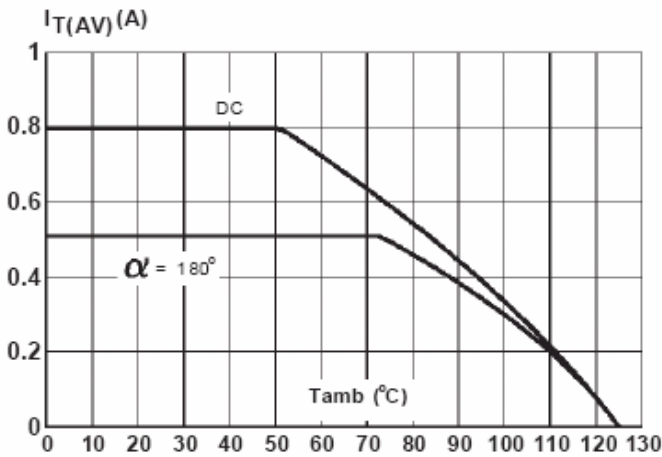


Fig.4 : Relative variation of thermal impedance junction to ambient versus pulse duration.

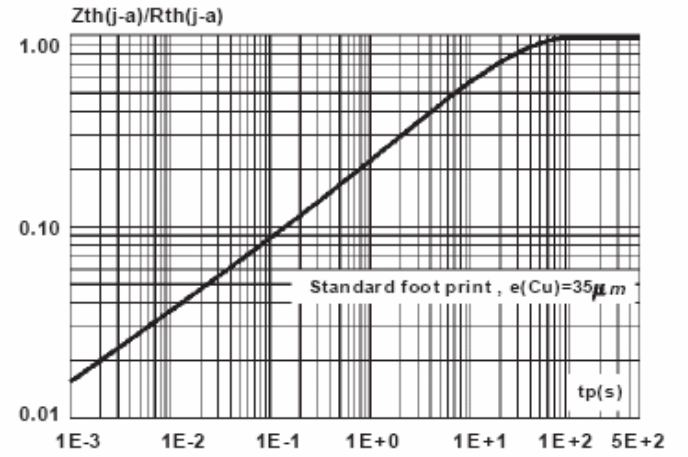


Fig.5 : Relative variation of gate trigger current and holding current versus junction temperature.

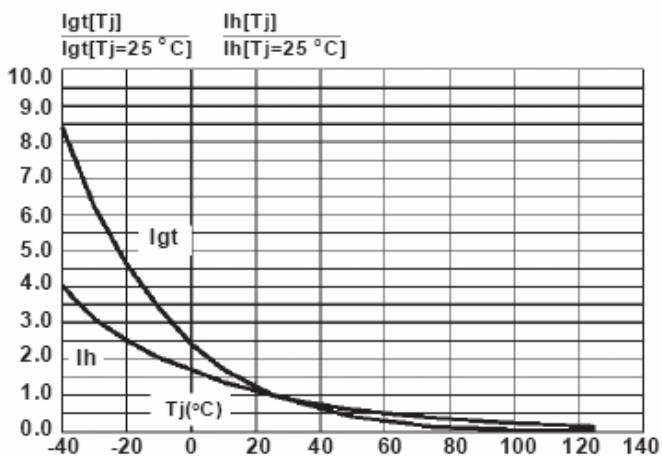


Fig.6 : Non repetitive surge peak on-state current versus number of cycles.

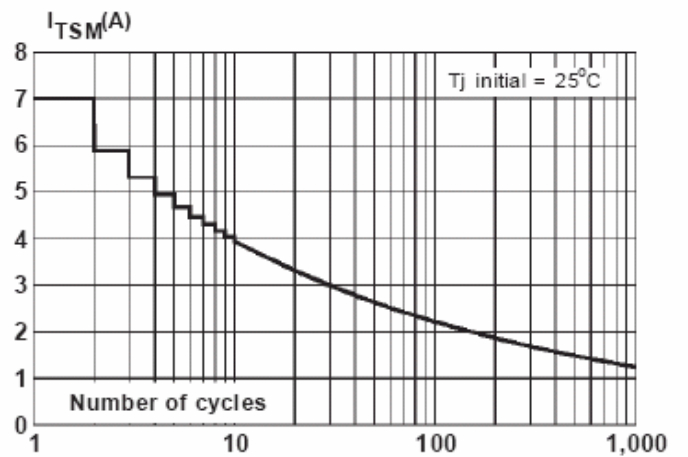


Fig.7 : Non repetitive surge peak on-state current for a sinusoidal pulse with width : t_p @ 10ms, and corresponding value of I^2t .

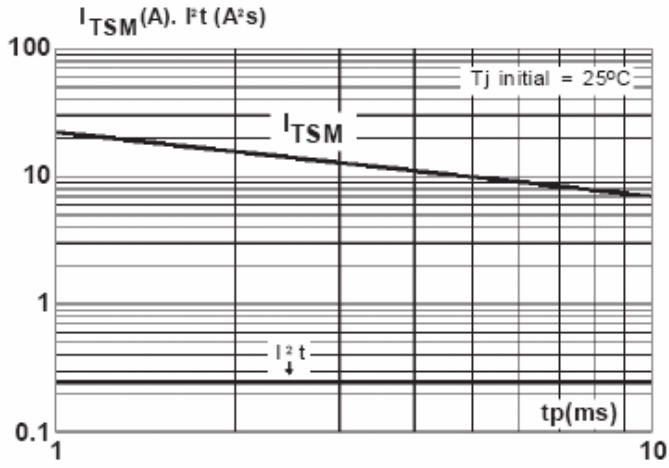


Fig.8 : On-state characteristics (maximum values).

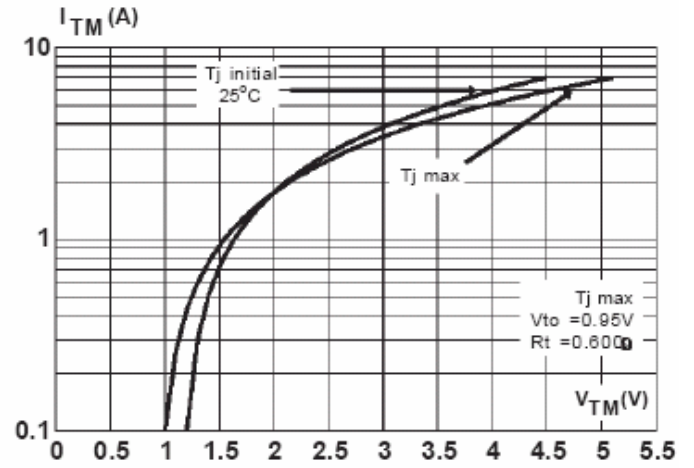


Fig.9 : Relative variation of holding current versus gate-cathode resistance (typical values).

